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58. (New) The wafer processor of claim 56 wherein the upper portion of the processor head extends outwardly over the upper edge of the processing bowl.
59. (New) The wafer processor of claim 56 wherein the motor is carried by the upper portion of the processor head.
60. (New) The wafer processor of claim 56 wherein the motor is enclosed within the upper portion of the processor head.
61. (New) The wafer processor of claim 54 wherein the processor head comprises an annular gas-receiving recess having a height above a height of a front surface of any wafer carried by the wafer support.
62. (New) The wafer processor of claim 54 wherein the wafer support comprises a wafer support plate.
63. (New) The wafer processor of claim 62 wherein the processor head has an upper portion which extends outwardly beyond the wafer support plate.
64. (New) The wafer processor of claim 54 wherein the wafer support comprises an acid-resistant material.
65. (New) The wafer processor of claim 64 wherein the acid-resistant material comprises polyvinylidene fluoride.
66. (New) The wafer processor of claim 54 wherein the wafer support comprises a wafer support plate having a downwardly directed front face and an upwardly directed back face.
67. (New) The wafer processor of claim 66 wherein the wafer support plate carries a plurality of fingers adapted to engage a peripheral edge of a wafer.
68. (New) The wafer processor of claim 67 wherein the fingers peripherally support the wafer.
69. (New) A wafer processor for processing a wafer such as a semiconductor wafer, a magnetic disk, or an optical disk, comprising:
 - a processing bowl having an upper edge; and
 - a processor head comprising an upper portion housing a motor, a rotatable wafer support carried below the upper portion, a vertical shaft coupling the motor to the wafer support, and a mount carried by the upper

portion, the wafer support being adapted to overlay and peripherally support a single wafer at a height below the upper edge of the processing bowl, the mount being adapted to facilitate lifting of the processor head with respect to the processing bowl.

70. (New) The wafer processor of claim 69 wherein the wafer holder extends downwardly from the upper portion of the processor head to position a wafer below the upper portion of the processor head.

71. (New) The wafer processor of claim 69 wherein the upper portion of the processor head extends outwardly of the periphery of the wafer.

72. (New) The wafer processor of claim 69 wherein the upper portion of the processor head extends outwardly over the upper edge of the processing bowl.

73. (New) The wafer processor of claim 69 wherein the motor is enclosed within the upper portion of the processor head.

74. (New) The wafer processor of claim 69 wherein the processor head comprises an annular gas-receiving recess having a height above a height of a front surface of any wafer carried by the wafer support.

75. (New) The wafer processor of claim 69 wherein the wafer support comprises a wafer support plate.

76. (New) The wafer processor of claim 69 wherein the wafer support comprises an acid-resistant material.

77. (New) The wafer processor of claim 76 wherein the acid-resistant material comprises polyvinylidene fluoride.

78. (New) The wafer processor of claim 69 wherein the wafer support comprises a wafer support plate having a downwardly directed front face and an upwardly directed back face.

79. (New) The wafer processor of claim 78 wherein the wafer support carries a plurality of fingers adapted to engage a peripheral edge of a wafer.

80. (New) The wafer processor of claim 79 wherein the fingers peripherally support the wafer.

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81. (New) A wafer processor for processing a wafer such as a semiconductor wafer, a magnetic disk, or an optical disk, comprising:

a processing bowl having an upper edge; and

a processor head comprising an upper portion, a motor enclosed within the upper portion, and a wafer holder extending downwardly from the upper portion, the motor being coupled to the wafer holder by a downwardly extending shaft, the wafer holder being adapted to overlay and peripherally support a single wafer at a height below the upper edge of the processing bowl with the upper portion of the processor head extending outwardly of the periphery of the wafer.

82. (New) The wafer processor of claim 81 wherein the processor head includes a mount adapted to facilitate lifting of the processor head.

83. (New) The wafer processor of claim 81 wherein the upper portion of the processor head extends outwardly over the upper edge of the processing bowl.

84. (New) The wafer processor of claim 81 wherein the processor head comprises an annular gas-receiving recess having a height above a height of a front surface of any wafer carried by the wafer support.

85. (New) The wafer processor of claim 81 wherein the wafer support comprises a wafer support plate.

86. (New) The wafer processor of claim 85 wherein the processor head has an upper portion which extends outwardly beyond the wafer support plate.

87. (New) The wafer processor of claim 81 wherein the wafer support comprises an acid-resistant material.

88. (New) The wafer processor of claim 87 wherein the acid-resistant material comprises polyvinylidene fluoride.

89. (New) The wafer processor of claim 81 wherein the wafer support comprises a wafer support plate having a downwardly directed front face and an upwardly directed back face.

90. (New) The wafer processor of claim 89 wherein the wafer support plate carries a plurality of fingers adapted to engage a peripheral edge of a wafer.

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91. (New) The wafer processor of claim 90 wherein the fingers peripherally support the wafer.
92. (New) A wafer processor for processing a wafer such as a semiconductor wafer, a magnetic disk, or an optical disk, comprising:
 - a processing bowl having an upper edge; and
 - a processor head comprising:
 - a motor carried in an upper housing;
 - a downwardly extending shaft coupled to the motor
 - a wafer holder coupled to and extending downwardly from the shaft, the wafer holder being adapted to overlay and peripherally support a single wafer for rotation by the motor at a height below the upper edge of the processing bowl.
93. (New) The wafer processor of claim 92 wherein the processor head includes a mount adapted to facilitate lifting of the processor head.
94. (New) The wafer processor of claim 92 wherein the upper portion of the processor head extends outwardly over the upper edge of the processing bowl.
95. (New) The wafer processor of claim 92 wherein the processor head comprises an annular gas-receiving recess having a height above a height of a front surface of any wafer carried by the wafer support.
96. (New) The wafer processor of claim 92 wherein the wafer support comprises a wafer support plate.
97. (New) The wafer processor of claim 96 wherein the processor head has an upper portion which extends outwardly beyond the wafer support plate.
98. (New) The wafer processor of claim 92 wherein the wafer support comprises an acid-resistant material.
99. (New) The wafer processor of claim 98 wherein the acid-resistant material comprises polyvinylidene fluoride.
100. (New) The wafer processor of claim 92 wherein the wafer support comprises a wafer support plate having a downwardly directed front face and an upwardly directed back face.

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101. (New) The wafer processor of claim 100 wherein the wafer support plate carries a plurality of fingers adapted to engage a peripheral edge of a wafer.
102. (New) The wafer processor of claim 101 wherein the fingers peripherally support the wafer.
103. (New) A method of handling a wafer, comprising:
 - providing a wafer processor comprising a processing bowl and a processor head, the processing head including a wafer support;
 - releasably engaging a periphery of a wafer with the wafer support;
 - positioning the wafer at a height below an upper edge of the processing bowl with the wafer support extending downwardly from a location positioned above the upper edge of the processing bowl, the processing head extending outwardly of the periphery of the wafer;
 - rotating the wafer at the height below the upper edge of the processing bowl; and
 - lifting the processing head.